Kingbright

5.0mm x 6.0mm BI-COLOR SURFACE MOUNT LED LAMP



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

AAA5060SUREVGEC HYPER RED / GREEN

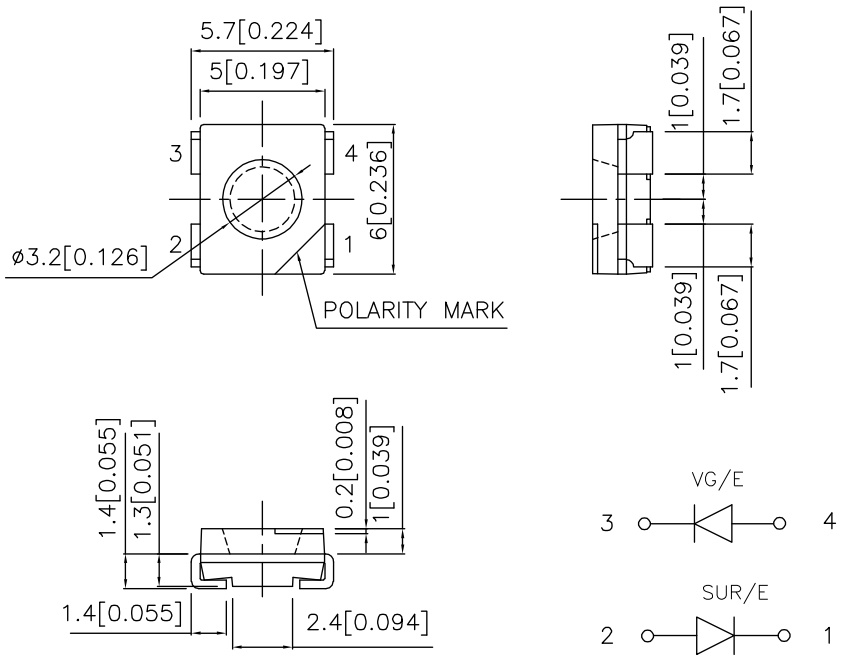
Features

- ●CHIPS CAN BE CONTROLLED SEPARATELY.
- ●SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- ●AVAILABLE ON TAPE AND REEL.
- ●PACKAGE: 500PCS / REEL.
- ●RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.
The Green source color devices are made with InGaN on SiC Light Emitting Diode.
Static electricity and surge damage the LEDS.
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @50mA*30 mA		Viewing Angle
			Min.	Typ.	2 θ 1/2
AAA5060SUREVGEC	HYPER RED (InGaAlP)	WATER CLEAR	380	700	100°
	GREEN (InGaN)		*280	*600	

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. * Luminous intensity with asterisk is measured at 30mA.

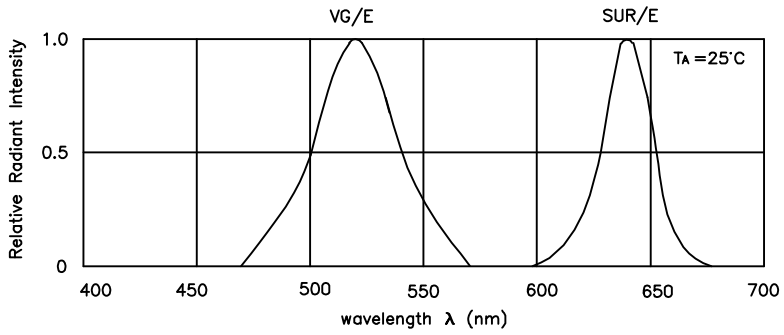
Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	640 518		nm	I_F=20mA
λD	Dominant Wavelength	Hyper Red Green	630 525		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	25 36		nm	I_F=20mA
C	Capacitance	Hyper Red Green	45 50		pF	V_F=0V;f=1MHz
V_F	Forward Voltage	Hyper Red Green	1.9 3.5	2.5 4.5	V	I_F=20mA
I_R	Reverse Current	All		10	uA	V_R = 5V

Absolute Maximum Ratings at T_A=25°C

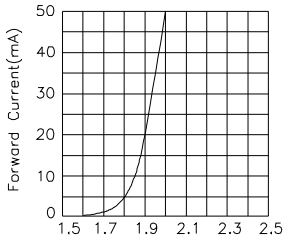
Parameter	Hyper Red	Green	Units
Power dissipation	125	135	mW
DC Forward Current	50	30	mA
Peak Forward Current [1]	200	150	mA
Reverse Voltage	5	5	V
Operating / Storage Temperature	-40°C To +85°C		

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

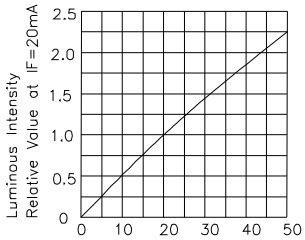


RELATIVE INTENSITY Vs. WAVELENGTH

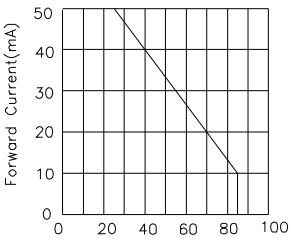
AAA5060SUREVGEC
Hyper Red



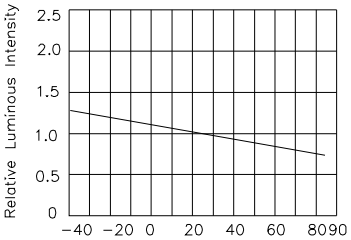
FORWARD CURRENT Vs.
FORWARD VOLTAGE



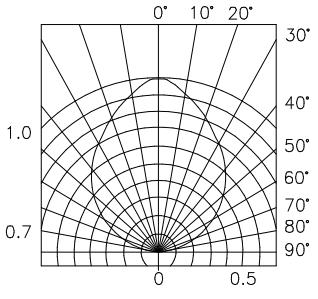
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE

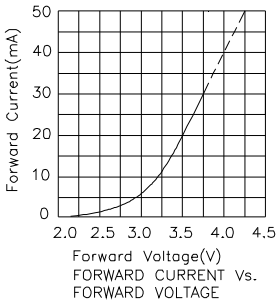


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

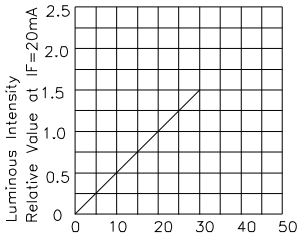


SPATIAL DISTRIBUTION

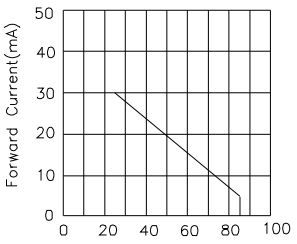
Green



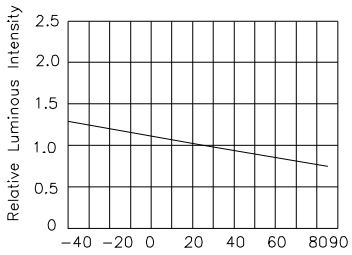
FORWARD CURRENT Vs.
FORWARD VOLTAGE



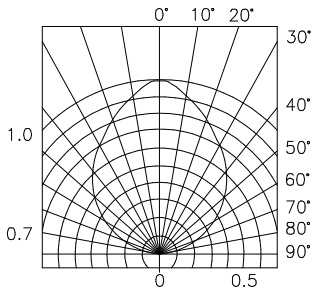
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



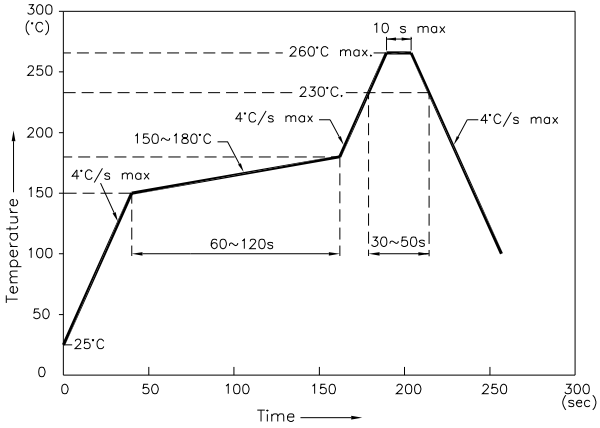
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

AAA5060SUREVGEC

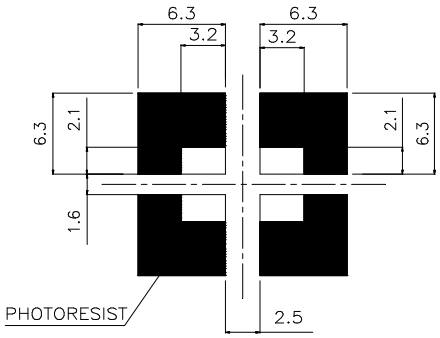
Reflow Soldering Profile For Lead-free SMT Process.



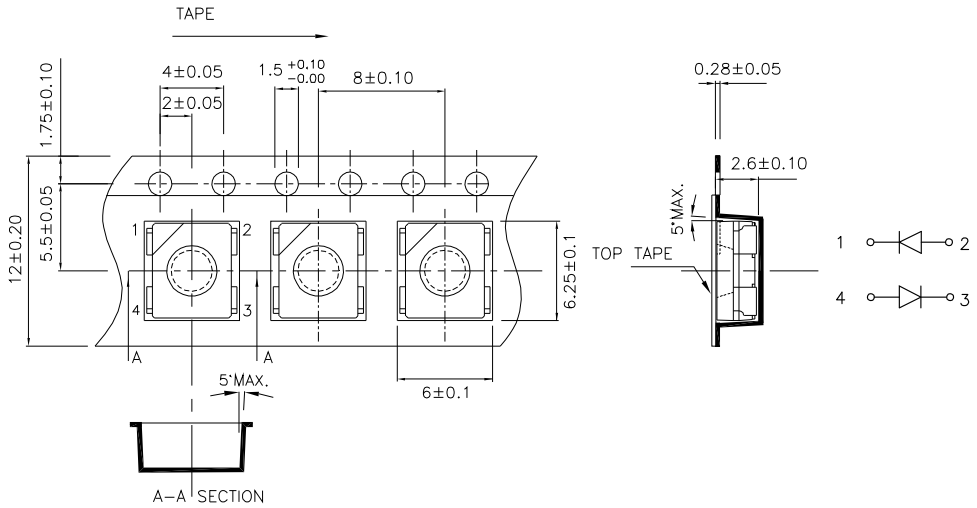
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)



If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.